

| Ref # | Hits    | Search Query                 | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|---------|------------------------------|---|------------------|---------|------------------|
| S4    | 22      | semix.as.                    | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/02/14 08:56 |
| S6    | 9       | SEMIX adj Incorporated.as.   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/02/14 08:57 |
| S7    | 9       | (SEMIX adj Incorporated).as. | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/02/14 08:59 |
| S8    | 152     | EBR and spin and apparatus   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/02/14 09:00 |
| S9    | 3825    | spin near coat               | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/02/14 09:15 |
| S10   | 1021    | EBR                          | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/02/14 09:00 |
| S11   | 101     | backside near rinse          | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/02/14 09:15 |
| S12   | 1       | S9 and S10 and S11           | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/02/14 09:03 |
| S15   | 4344066 | apparatus                    | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/02/14 09:03 |
| S16   | 7       | two near nozzel              | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2006/02/14 09:12 |

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| S18 | 1     | "10/826487"  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 09:12 |
| S19 | 13835 | two near nozzle  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 09:13 |
| S20 | 38    | S9 and S19   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 09:14 |
| S22 | 413   | backside same rinse  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 09:15 |
| S24 | 24    | S9 and S15 and (EBR or (edge adj bead adj removal))            | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 09:23 |
| S26 | 19    | S24 and nozzle   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 09:19 |
| S27 | 10    | S24 and (two near nozzle)                                      | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 09:20 |
| S28 | 9     | S24 and (three near nozzle)                                    | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 09:23 |
| S29 | 600   | water and (EBR or (edge adj bead adj removal))                 | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 09:23 |
| S30 | 4     | (dispense near water) and (EBR or (edge adj bead adj removal)) | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 10:37 |

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| S31 | 3868 | water and simultaneous and etch | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 10:03 |
| S33 | 380  | S31 and dispense                | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 10:04 |
| S34 | 218  | S33 and nozzle                  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 10:04 |
| S35 | 72   | S34 and etchant                 | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 10:04 |
| S37 | 6403 | protect near substrate          | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 10:37 |
| S38 | 8437 | DI adj water                    | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 10:37 |
| S40 | 3    | S37 same S38                    | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 10:38 |
| S41 | 98   | S37 and S38                     | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 10:40 |
| S44 | 60   | (water) near protectant         | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 12:47 |
| S45 | 4    | S44 and semiconductor           | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 10:42 |

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| S50 | 270865  | sulfuric                           | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 10:48 |
| S51 | 1323    | EBR or (edge adj bead adj removal) | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 10:48 |
| S52 | 248054  | hydrochloric                       | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 10:49 |
| S53 | 128053  | S50 and S52                        | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 10:49 |
| S54 | 44      | S51 and S53                        | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:02 |
| S55 | 75      | (water) near passivation           | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 12:53 |
| S56 | 21      | S55 and semiconductor              | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 12:55 |
| S58 | 221     | (water) near (pre adj treatment)   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 12:54 |
| S62 | 537     | prepare near surface same water    | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 12:54 |
| S63 | 1622044 | semiconductor                      | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 12:55 |

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| S64 | 34      | S58 and S63  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 12:55 |
| S65 | 87      | S62 and S63  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 12:55 |
| S66 | 5333662 | "1" near fluid near drop near three<br>near seconds to about S55 fluid<br>drop every "second." | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:03 |
| S68 | 1       | about near "1" near fluid near drop<br>near every near second                                  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:03 |
| S69 | 86      | "1" near drop near second  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:04 |
| S70 | 41      | S69 same (DI or water)   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:06 |
| S71 | 14      | (EBR and apparatus).ab.  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:12 |
| S72 | 0       | SOB and EBR  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:11 |
| S73 | 3786495 | G  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:11 |
| S74 | 37      | SOG and EBR  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:14 |

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| S76 | 2      | (resist and spin and EBR).ab.                              | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:15 |
| S77 | 80     | ((resist and spin and EBR) and apparatus)                  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:16 |
| S78 | 14     | (resist and spin and EBR) and (apparatus).ti.              | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:17 |
| S79 | 50     | (edge adj bead adj removal).ti.                            | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:29 |
| S80 | 4      | S79 and drop   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:20 |
| S81 | 75     | (edge adj bead adj removal) and drop                       | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:26 |
| S82 | 400    | (edge adj bead adj removal) and (drops per second)         | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:28 |
| S83 | 397371 | "1" near (drops per second)                                | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:28 |
| S84 | 49     | S82 and S83  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:27 |
| S85 | 1      | (edge adj bead adj removal) and (drops adj per adj second) | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:28 |

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| S86 | 451196 | (flow adj rate)             | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:45 |
| S87 | 474    | (edge adj bead adj removal) | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:45 |
| S88 | 135    | S86 and S87                 | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:29 |
| S89 | 0      | program near S87            | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:45 |
| S90 | 44     | TEI and SOG                 | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:45 |
| S91 | 1      | S90 and S87                 | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:48 |
| S92 | 0      | HCL near EBR and MI/min     | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:48 |
| S93 | 0      | HCL near EBR                | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:48 |
| S94 | 1      | HCL same EBR                | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:48 |
| S95 | 65     | HCL and EBR                 | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 14:48 |

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| S96      | 3  | S95 and ml/min                 | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 15:08 |
| S97      | 48 | (pulsing near water) and clean | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 15:09 |
| S98      | 6  | S97 and semiconductor          | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 15:09 |
| S99      | 68 | (pulsed near water) and clean  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 15:10 |
| S10<br>0 | 7  | S99 and semiconductor          | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 15:13 |
| S10<br>1 | 0  | sccm near (DI adj water)       | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 15:14 |
| S10<br>2 | 28 | sccm same (DI adj water)       | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 15:21 |
| S10<br>3 | 2  | "6793836".pn.                  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 15:30 |
| S10<br>4 | 2  | puddle near etch near solution | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 15:31 |
| S10<br>5 | 5  | puddle near etchant            | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 15:31 |



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| S10<br>6 | 450 | water near puddle | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 15:31 |
| S10<br>7 | 6   | S106 and wafer    | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 15:33 |
| S10<br>8 | 195 | wafer near scrub  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 15:34 |
| S10<br>9 | 66  | S108 and Di       | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2006/02/14 15:34 |